

## SCM Series

### Features

Low profile and very small size SMD Design,  
Wound Chip constructure with standard 453226 to  
453228 size, with best EMI suppression effect but  
least impact to data signal wave form.

### Applications

Preventive measure against high speed signal  
radiation emissions such as USB 2.0,  
IEEE1394 or LAN interface.  
Best for NB,DSC,mobile device design.

### Product Identification

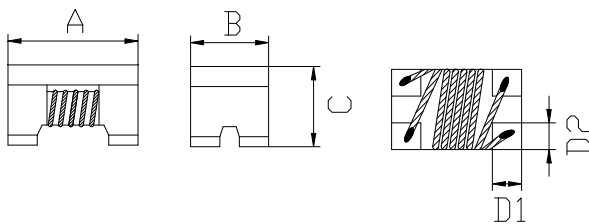
SCM XXXXXX LTL - XXX  
For example:SCM453226LTL-101

### General Specifications

Test frequency.....100KHz  
Test Voltage.....100mV  
Test frequency.....10MHz  
Parameters Test Temp..... 25℃  
Operation Temp.....-20℃ to +105℃  
(Including temperature Rise)  
Storage Temp.....0~40℃  
Storage Humidity.....<70% RH  
Resistance to Soldering Heat.....260℃ for 10 sec  
Temperature Rise.....40℃ Typ. at Rated Current

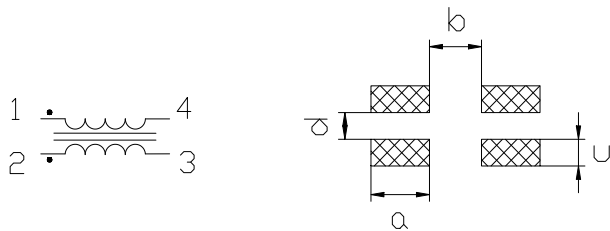
## Shape And Dimensions

## Dimensions In mm



TYPE	A	B	C	D1	D2	a	b	c	d
	±0.2	±0.2	±0.2	Ref	Ref	Ref	Ref	Ref	Ref
453226	4.50	3.20	2.60	1.00	1.00	1.40	2.10	1.60	0.40
453228	4.50	3.20	2.80	1.00	1.00	1.40	2.10	1.60	0.40

## Electrical Schematic & PAD Layout



## Standard Specifications

Stamp	Inductance (uH) (100KHz/100mV)	Tolerance	Impedance (Ω)TYP 10MHz	DC Resistance (Ω) Max	Rated Current (mA) Max
SCM453226LTL-101	100	+50(-30)%	5800	2.0	250
SCM453228LTL-110	11	+50(-30)%	600	0.6	250
SCM453228LTL-220	22	+50(-30)%	1200	1.0	200
SCM453228LTL-510	51	+50(-30)%	2800	1.0	200

\*All the data listed in this catalogue are for reference only, JENG SHI reserves the right to alter or revise the specifications without prior notification.

\*Beyond the above specification also can meet the special requirements. Need detailed content Please to the website query or contact us.

